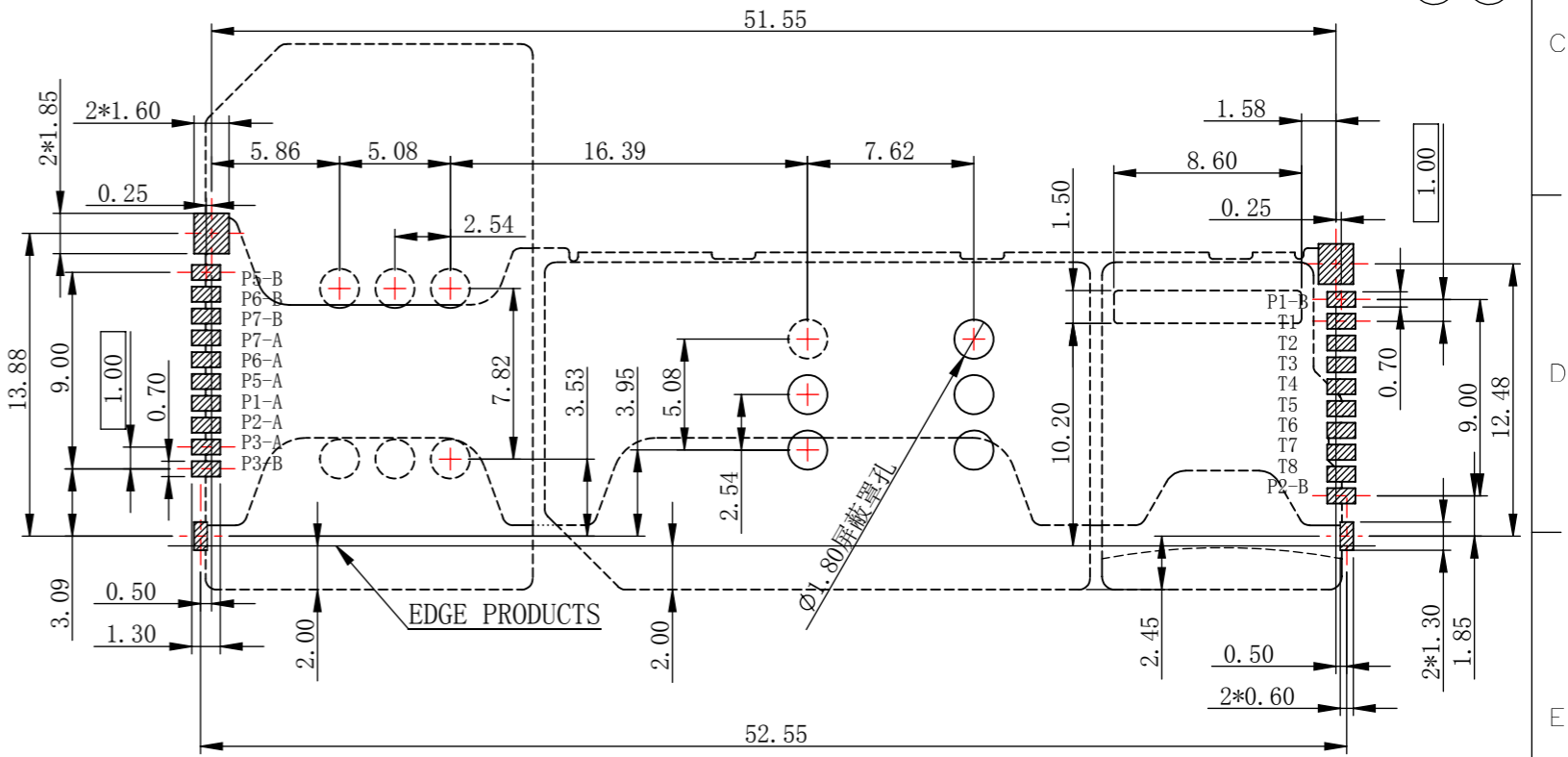


- NOTES:
- MATERIAL:
HOUSING: LCP, BLACK, UL 94V-0
CONTACT: PHOSPHORBRONZE, T=0.15MM
SHELL: STAINLESS STEEL T=0.20MM
 - FINISH
CONTACT: 50U'' MIN PLATING OVER ALL
GOLD FLASH ON THE CONTACT AREA AND SOLDER AREA
SHELL: SELECTIVE GOLD FLASH IN SOLDER TAIL AREA
50U'' NI MIN. PLATING OVER ALL
 - GP PASSED ACCORD WITH HRD-RoHS-219 STANDARD.
 - ALL DIMENSIONS MARKED ▼ MUST BE CONTROLLED BY QC
 - ALL DIMENSIONS MARKER (XX) MUST BE MEASURE BY FAI.
 - RATED PARAMETERS OF CONNECTOR
4-1. Operating temperature: -40°C to 70°C
4-2. Rated Current: 0.5A
4-3. Rated Voltage: 30V DC Per Contact
 - ELECTRICAL MECHANICAL ENVIRONMENTAL
5-1. Dielectric withstanding Voltage : 500V AC 1min.
5-2. Insulation Resistance: 1000 MΩMin.
5-3. Normal Force: 100g Min. Per Pin
5-4. Durability: 1000 cycles
5-5. Heat Resistance: 20mΩ MAX.

T-CARD PIN NO.	PIN NO.
T1	DAT2
T2	CD/DAT3
T3	CMD
T4	VDD
T5	CLK
T6	VSS
T7	DATO
T8	DAT1
SIM CARD PIN NO.	PIN NO.
P1-A/B	VCC
P2-A/B	RST
P3-A/B	CLK
P5-A/B	GND
P6-A/B	VPP
P7-A/B	I/O



RECOMMENDED P.C.B LAYOUT
TOLERANCE: ±0.05MM

				UNITS: mm	GENERAL TOLERANCE		DRAW:	PART NO: S23-2B20F36A
				DATE: 09/23'2014	X. ±0.25	X° ±2.00°	CHECKED:	TITLE: DOUBLE SIM CARD + T-CARD H=3.65mm DOUBLE SIM 防烫pin结构
				SCALE: 3:1	.X ±0.15	.X° ±1.00°	APPROVE:	DRAWING NO:
				SHEET: 1/1	.XX ±0.10	.XX° ±0.50°		
B	E1608313A	修改图面与实物一致	08/04/2016	REV. A	.XXX ±0.05	.XXX° ±0.10°		
REV.	ECN NO.	DESCRIPTION	DATE	REV.	MATERIAL:	FINISH: SEE NOTE	昆山捷皇电子精密科技有限公司 HONGRIDA ELECTRONIC TECHNOLOGY CO.,LTD.	